connecting portion, and a surface acoustic wave absorbing member formed outside of the element wiring connecting portion, and the first element surface being disposed in an opposite relation with respect to the first board surface;

a conductive connecting member disposed between the board wiring connecting portion and the element wiring connecting portion; and

a sealing member configured to seal a space portion formed between the first board surface and the first element surface and to alone prevent the sealing member from spreading into the space portion.

167. (Amended) The surface acoustic wave device as set forth in Claim 166, wherein a difference between the first thickness and the second thickness is in the range of from 5 μm to 100 μm.

168. (Amended) A surface acoustic wave device, comprising:

a printed circuit board possessing a first region and a second region which is larger in thickness than the first region, the second region including a board wiring connection portion;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, an element wiring connecting portion and a surface acoustic wave absorbing member, and being disposed with a face-down arrangement so that the surface acoustic wave absorbing member is disposed in an opposite relation with respect to the first region of the printed circuit board;

a conductive connecting member disposed between the board wiring connecting portion and the element wiring connecting portion; and

a sealing member configured to seal a space portion formed between the first board surface and the first element surface and to alone prevent the sealing member from spreading into the space portion.

169. (Amended) The surface acoustic wave device as set forth in Claim 168 wherein a difference in thickness between the first region and the second region of the printed circuit board is in the range of from 5 μm to 500 μm.

170. (Amended) A surface acoustic wave device, comprising:

a printed circuit board possessing a first board surface and a second board surface, the first board surface having a board wiring pattern;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, an element wiring connecting portion and a surface acoustic wave absorbing member, and the first element surface being disposed in an opposite relation with respect to the first board surface;

a conductive connecting member disposed between the board wiring pattern and the element wiring connecting portion, the conductive connecting member being composed of a plurality of bumps stacked so as to determine a spacing between the board wiring pattern and the element wiring pad; and

a sealing member configured to seal a space portion formed between the first board surface and the first element surface and to alone prevent the sealing member from spreading into the space portion.